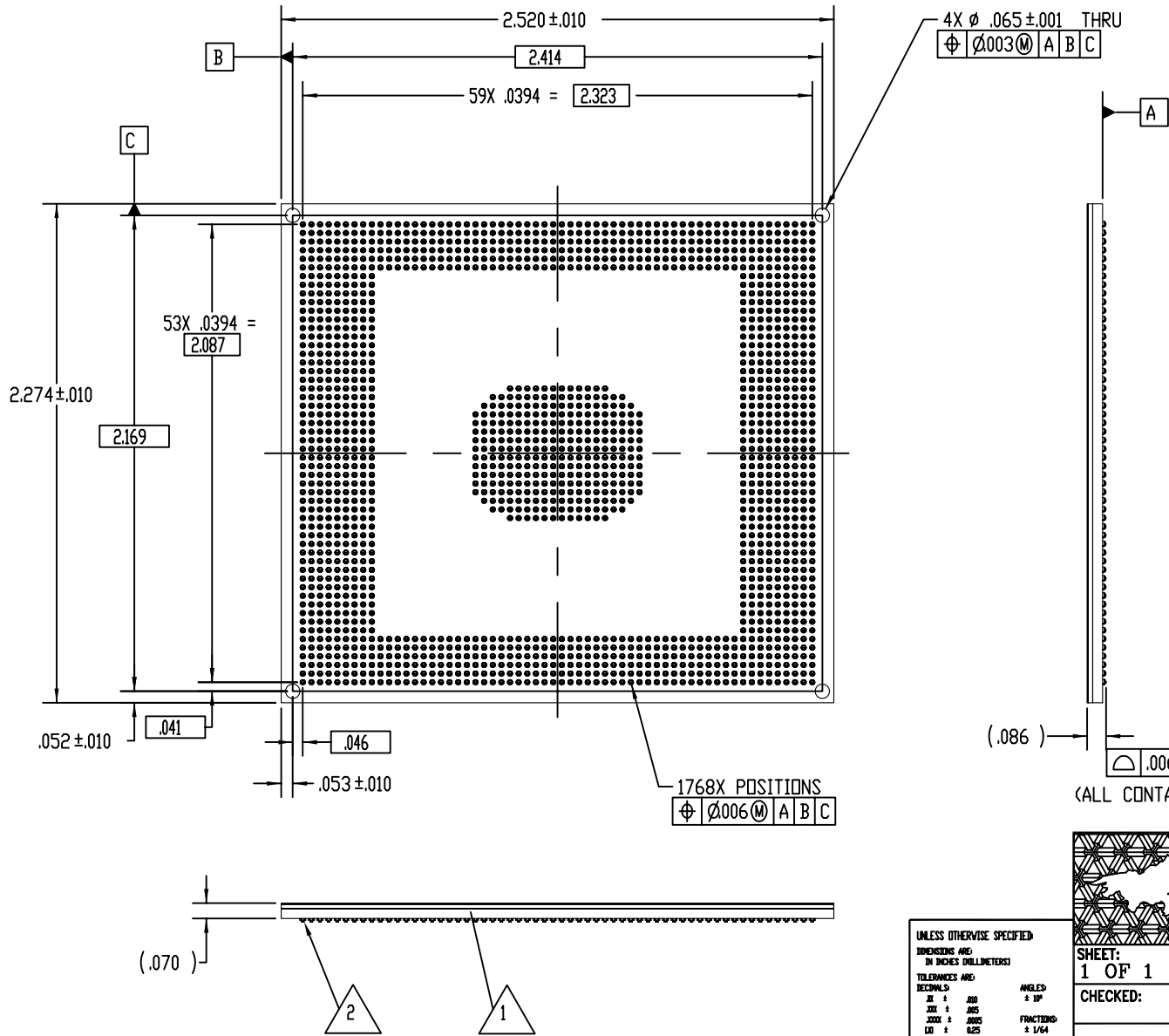


REV	DESCRIPTION	DATE	BY
A	NEW DRAWING	05/17/07	H.N.
B	ADDED PACKAGE SPECIFICATIONS	06/01/07	H.N.

F7976



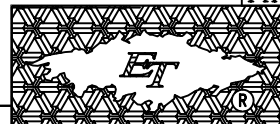
- NOTES:
- INSULATOR MATERIAL: FR4, BLACK.
 - CONTACT MATERIAL: BERYLLIUM COPPER.
CONTACT PLATING: HARD GOLD OVER NICKEL.
 - REFER TO ET HILO APPLICATION GUIDELINES FOR LAND PATTERN, STENCIL DESIGN, AND KEEP OUT ZONE RECOMMENDATIONS.

RoHS Compliant

PACKAGE SPECIFICATIONS	
PIN COUNT	= 1768
LEAD PITCH	= 1.00mm
GRID SIZE	= 54X60
PACKAGE SIZE	= 58.00X64.00mm

Emulation Technology, Inc.
— VLSI and SMT ADAPTERS and ACCESSORIES —

2344 Walsh Avenue, Bldg.F Santa Clara, Ca 95051
TEL:(408)982-0660 FAX:(408)982-0664



UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES (MILLIMETERS)
TOLERANCES ARE:
X.X ± .010 ANGLES ± 1°
X.XX ± .005 FRACTIONS ± 1/64
X.XX ± .005
X.XX ± .005
X.XX ± .005

SHEET: 1 OF 1	DATE: 05/17/07	REVISION: B	ASSEMBLY DRAWING
CHECKED:	DRAWN: H.N.	ITEM: HLS-001768-B-10	
Scale N/A	DO NOT SCALE DRAWING	DESCRIPTION: HLS-001768-B-10	